

DIALOG(R)File 352:Derwent WPI

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XRAM Acc No: C1995-031566

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**Saponified EVA compsn contg polyamide resin - used for heat-resistance packaging material**

Patent Assignee: NIPPON SYNTHETIC CHEM IND CO (NISY)

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**Patent Family** (2 patents, 1 countries)

Patent			Application			
Number	Kind	Date	Number	Kind	Date	Update
JP 6345920	A	19941220	JP 1993164013	A	19930608	199510 B
JP 3361359	B2	20030107	JP 1993164013	A	19930608	200306 E

Priority Applications (no., kind, date): JP 1993164013 A 19930608

**Patent Details**

Number	Kind	Lan	Pg	Dwg	Filing Notes
JP 6345920	A	JA	8	0	
JP 3361359	B2	JA	7		Previously issued patent JP 06345920

**Alerting Abstract** JP A

A saponified EVA copolymer(EVOH) compsn. (I) comprises 100 pts.wt of a mixture comprising (A) 70-96 wt.% of EVOH having an ethylene content of 20-60 mol.% and a saponification degree of more than 90 mol.% and (B) 30-4 wt.% of a terminal-adjusted polyamide resin comprising a caproamide, in which the ratio of methylene groups/amide groups satisfies a relationship: CH<sub>2</sub>/NHCO is 5.20-6.50 and a terminal carboxyl group content (X microeq.g) and a terminal amino group content (Y microeq./g) satisfy a relationship: (Y) is less than (X)+% by the use of a terminal adjustor, such as benzoic acid, mixed with (C) 0.1-1 pts.wt. of a hindered phenol compound and (D) 0.5-15 micromol/g(metal conversion) of an alkaline earth metal aliphatic carboxylate.

Also claimed is a coextruded laminate(II) prepared by laminating polyamide resin layers on both sides of (I) layer. The polyamide resin is a blend of nylon 6 and an amorphous polyamide. (II) is packaging material which can be subjected to retort or boil disinfection.

USE/ADVANTAGE - (II) is used for packaging material. (I) has a high heat resistance. (II) has a high ply adhesion and can be subjected to a retort or boil disinfection.

**Title Terms** /Index Terms/Additional Words: SAPONIFICATION; EVA;  
COMPOSITION;

CONTAIN; POLYAMIDE; RESIN; HEAT; RESISTANCE; PACKAGE; MATERIAL

**Class Codes**

International Classification (Main): C08L-023/08, C08L-023/26

(Additional/Secondary): B29C-047/06, B29K-029/00, B32B-027/08, B32B-027/28  
, C08K-005/09, C08K-005/098, C08K-005/13, C08L-029/04, C08L-077/00

File Segment: CPI; EngPI

DWPI Class: A17; A23; A92; P73

Manual Codes (CPI/A-M): A05-F01E3; A07-A04E; A10-E09B; A10-E23; A11-B09A2;  
A12-P01A; A12-S06C1; A12-S07A

**Chemical Indexing**

Specific Compound Numbers: R00326; R00258

Derwent Chemistry Resource Numbers: (Linked) 1013-DIS; 168-DIS; 1013; 168

**Key Word Indexing**

\*1\* 1013-DIS 168-DIS

**Polymer Indexing**

<01>

\*001\* 017; G0044 G0033 G0022 D01 D02 D12 D10 D51 D53 D58 D82 R00326-R  
1013-R; H0011-R; P1694-R D01; P1332 P1694; S9999 S1285-R; S9999 S1581  
; P1150

\*002\* 017; Q9999 Q8366-R; B9999 B4682 B4568; N9999 N6871 N6655; Q9999  
Q7818-R; N9999 N7192 N7023; N9999 N5981 N5970; K9745-R; K9574 K9483;

K9698 K9676; B9999 B5301 B5298 B5276; ND04; ND01  
\*003\* 017; D01 F30-R; A999 A511 A486; A999 A771  
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\*001\* 017; D01 D11 D10 D50 D86 F70; P0635-R F70 D01; S9999 S1285-R; S9999  
S1581; M9999 M2153-R; M9999 M2028; P0646 P0635 F70 D01 D11 D10 D50  
D86  
\*002\* 017; B9999 B4751 B4740; Q9999 Q8366-R; B9999 B4682 B4568; N9999  
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K9574 K9483; K9698 K9676; B9999 B5301 B5298 B5276; ND04; ND01  
\*003\* 017; D01 D19 D18 D31 D50 D60 D87 F36 F35 R00258-R 168-R; H0226  
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K9698 K9676; B9999 B5301 B5298 B5276; ND04; ND01; K9712 K9676; B9999  
B4784 B4773 B4740  
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\*002\* 017; Q9999 Q8366-R; B9999 B4682 B4568; N9999 N6871 N6655; Q9999  
Q7818-R; N9999 N7192 N7023; N9999 N5981 N5970; K9745-R; K9574 K9483;  
K9698 K9676; B9999 B5301 B5298 B5276; ND04; ND01; K9712 K9676

**Original Publication Data by Authority**

**Japan**

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**\*\*SAPONIFIED ETHYLENE-VINYL ACETATE COPOLYMER RESIN COMPOSITION AND  
COEXTRUSION LAMINATE HAVING LAYER FORMED THEREFROM\*\***

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C08K-5/13(B) C08L-29/04(B) C08L-77/00(B) B29K-29:00(Z)

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